

**REMARKS**

Claims 2-8 and 13-17 have been amended. Claims 18-21 have been added. Claim 9 has been cancelled. Claims 2-8 and 13-21 remain for further consideration. No new matter has been added.

The objections and rejections shall be taken up in the order presented in the Official Action.

1. The drawings currently stand objected to.

The drawings have been amended.

2. Claims 2-8 and 13-15 currently stand objected to for informalities.

Claims 2-8 and 13-15 have been amended.

- 4-5. Claims 8 and 15 currently stand rejected for allegedly failing to point out and distinctly claim the subject matter deemed to be present in the invention.

Claims 8 and 15 have been amended.

7. Claims 16, 2, 3, 6 and 7 currently stand rejected under 35 U.S.C. §102(b) for allegedly being anticipated by U.S. Patent 5,365,409 to Kwon (hereinafter “Kwon”).

#### Claim 16

As amended, claim 16 recites an integrated circuit, which includes:

“a semiconductor die;

a carrier device comprising a die paddle onto which the die is attached and a plurality of metallic leads each comprising an inner lead portion that extends to an outer lead portion, where a plurality of stamped pedestals are arranged on the carrier device exteriorly surrounding and adjacent to the die paddle, where the carrier device, the die paddle and the stamped pedestals form a single piece unitary structure;

a first bond wire extending from the die to a first of the plurality of stamped pedestals, and a second bond wire extending from the first of the plurality of stamped pedestals to an inner lead portion; and

a package that encapsulates the semiconductor die, the die paddle, the first and second bond wires and the inner lead portions.” (emphasis added, cl. 16)

The Official Action contends that “*the term stamped... indicates a process of forming the pedestals. The patentability of a product does not depend on the method of its production. See MPEP 2113. The pedestals 158 may be formed by “stamping” the pattern from a larger sheet.*” (page 4, lines 8-11). However, this is an improper reading of claim 16 and Kwon. Kwon teaches that an “electrically-insulated, heat-conducting ceramic substrate 152 has an integrated-circuit die 154 attached to its upper surface. The bonding fingers 156 of a leadframe are also attached to the upper surface of the ceramic substrate 152. Intermediate conductive traces, or interposers, 158 are deposited on the upper surface of the ceramic substrate 152 using, for example, thin-film deposition techniques or thick-film printing techniques.” (col. 6, lines 52-60, emphasis added). Significantly, the intermediate conductive traces/interposers 158 are composed of a material, which is a separate and distinct material from the ceramic substrate. The intermediate conductive traces/interposers 158 in Kwon are incapable of forming a single piece

unitary structure with the ceramic substrate, because they are deposited onto the substrate surface by thin-film deposition or thick-film printing techniques, and are a separate and distinct material from that of the ceramic substrate.

A 35 U.S.C. §102(b) rejection requires that a single prior art reference disclose each feature of the claimed invention. Kwon is incapable of anticipating the subject matter of claim 16 since it fails to disclose the claimed feature of *"the carrier device, the die paddle and the stamped pedestals form a single piece unitary structure"*. (cl 16).

### **Claim 2-3 and 6-7**

It is respectfully submitted that this rejection is now moot since claims 2-3 and 6-7 depend directly on claim 16, which is allowable for at least the reasons set forth above.

10. Claims 17, 4, 5, 9, 13 and 14 currently stand rejected for allegedly being obvious in view of Kwon.

### **Claim 17**

As amended, claim 17 recites an integrated circuit, which includes:

“a semiconductor die;

a metallic carrier device comprising a planar surface onto which the die is attached and a plurality of metallic leads each comprising an inner lead portion that extends to an outer lead portion, where a plurality of stamped pedestals are arranged on the carrier device exteriorly surrounding and adjacent to the planar surface, where the carrier device, the die paddle and the stamped pedestals form a single piece unitary structure; and

a first bond wire extending from the die to a first of the plurality of stamped pedestals, and a second bond wire extending from the first of the plurality of stamped pedestals to an inner lead portion.” (emphasis added, cl. 17).

The Official Action contends that “*the term stamped... indicates a process of forming the pedestals. The patentability of a product does not depend on the method of its production. See MPEP 2113. The pedestals 158 may be formed by “stamping” the pattern from a larger sheet.*” (page 9, lines 3-6). However, this is an improper reading of claim 16 and Kwon. Kwon teaches that an “electrically-insulated, heat-conducting ceramic substrate 152 has an integrated-circuit die 154 attached to its upper surface. The bonding fingers 156 of a leadframe are also attached to the upper surface of the ceramic substrate 152. Intermediate conductive traces, or interposers, 158 are deposited on the upper surface of the ceramic substrate 152 using, for example, thin-film deposition techniques or thick-film printing techniques” (col. 6, lines 52-60, emphasis added). Significantly, the intermediate conductive traces/interposers 158 are composed of a material, which is a separate and distinct material from the ceramic substrate. The intermediate conductive traces/interposers 158 in Kwon are incapable of forming a single piece unitary structure with the ceramic substrate, because they are deposited onto the substrate surface by thin-film deposition or thick-film printing techniques, and are a separate and distinct material from that of the ceramic substrate.

A 35 U.S.C. §102(b) rejection requires that a single prior art reference disclose each feature of the claimed invention. Kwon is incapable of anticipating the subject matter of claim 16 since it fails to disclose the claimed feature of “*the carrier device, the die paddle and the stamped pedestals form a single piece unitary structure*”. (cl 17).

**Claims 4-5 and 13-14**

It is respectfully submitted that this rejection is now moot since claims 4-5 and 13-14 depend directly on either claim 16 or claim 17, both of which are allowable for at least the reasons set forth above.

11. Claims 8 and 15 currently stand rejected for allegedly being obvious in view Kwon and U.S. Patent 6,365,976 to Carter (hereinafter "Carter").

**Claims 8 and 15**

It is respectfully submitted that this rejection is now moot since claims 8 and 15 depend directly on claim 16, which is allowable for at least the reasons set forth above.

For all the foregoing reasons, reconsideration and allowance of claims 2-8 and 13-21 is respectfully requested.

If a telephone interview could assist in the prosecution of this application, please call the undersigned attorney.

Respectfully submitted,



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